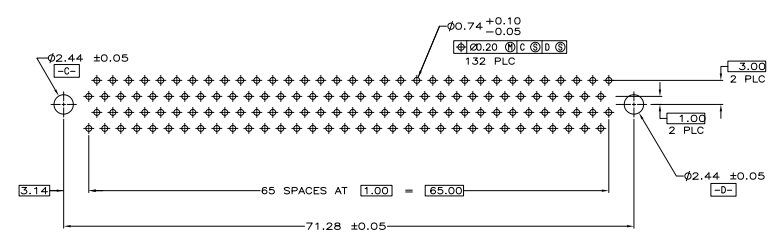
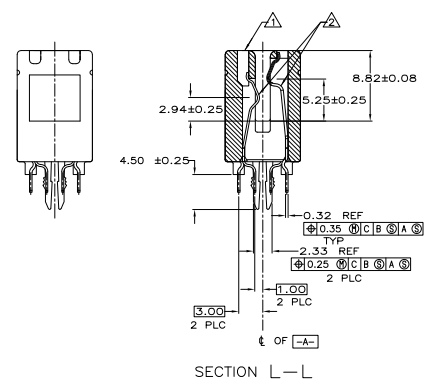
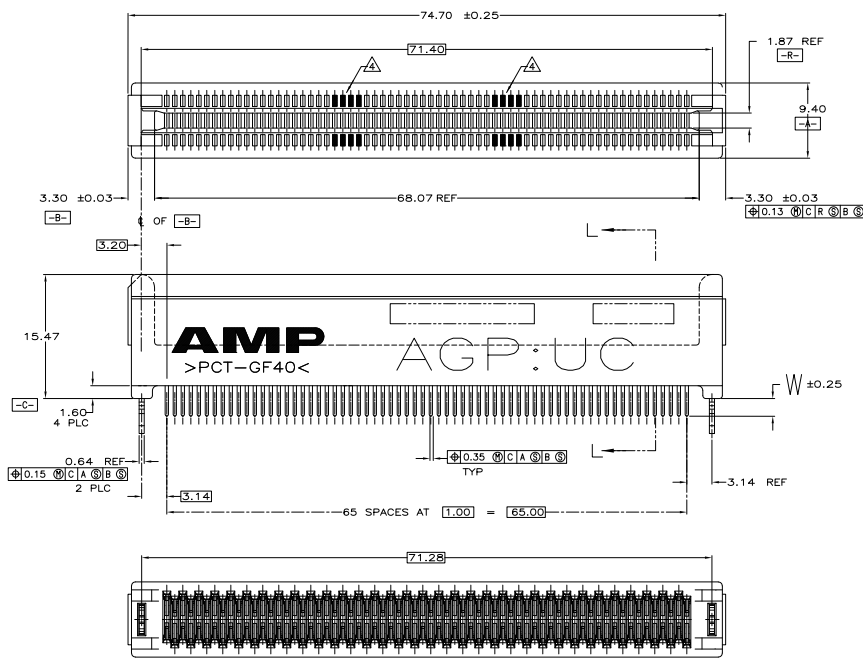


| REVISONS | | DATE | BY | APP'D |
|----------|---------------------------|----------|----|-------|
| C | REVISED PER QCS1-0008-99 | 06/09/99 | RB | DD |
| D | REV PER QCS1-0062-99 | 05/18/99 | MM | EL |
| D1 | REVISED ECR-09-010118 | 06/07/99 | AJ | ST |
| D2 | REVISED PER ECD-09-020689 | 3/14/00 | KK | AEC |



RECOMMENDED CONNECTOR MOUNTING HOLE PATTERN
 (CONNECTOR SIDE SHOWN)

- △ MATERIAL: HOUSING, THERMOPLASTIC, COLOR: BROWN. CONTACTS, PHOSPHOR BRONZE. HOLD-DOWNS, BRASS.
- △ FINISH: CONTACTS, 1.27 MIN. MICROMETERS NICKEL ALL OVER, 0.38 MIN. MICROMETERS GOLD OVER NICKEL IN CONTACT AREA, 2.54 MIN MICROMETERS TIN-LEAD OVER NICKEL ON SOLDER TAILS.
- 3. REFER TO INTEL ACCELERATED GRAPHICS PORT INTERFACE SPECIFICATION FOR RECOMMENDED MATING PAD PATTERNS FOR AGP 1X, 2X AND 4X BOARDS.
- △ SHADED CONTACT LOCATIONS ARE AT RISK OF DAMAGE DURING MATING AND UNMATING WITH AGP-1X AND AGP-2X/4X CIRCUITS.
- △ FINISH: CONTACTS, 1.27 MIN. MICROMETERS NICKEL ALL OVER, 0.0254-0.0762 MICROMETERS GOLD OVER NICKEL IN CONTACT AREA, 2.54 MIN. MICROMETERS TIN-LEAD OVER NICKEL ON SOLDER TAILS.
- △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINIS!

| | | | |
|------------|---|------|----------|
| △ OBSOLETE | △ | 3.18 | 145376-6 |
| △ OBSOLETE | △ | 2.54 | 145376-5 |
| △ | △ | 3.18 | 145376-3 |
| △ | △ | 2.54 | 145376-2 |
| △ OBSOLETE | △ | 2.16 | 145376-1 |
| PLATING | | W | PART NO |

THIS DRAWING IS A CONTROLLED DOCUMENT.

| | | | |
|-------------|-------|-----|-------|
| DESIGNED BY | DATE | BY | DATE |
| AMP | 02/98 | AMP | 02/98 |
| BY | DATE | BY | DATE |
| AMP | 02/98 | AMP | 02/98 |
| BY | DATE | BY | DATE |
| AMP | 02/98 | AMP | 02/98 |

ASSEMBLY, 132 POSITION
 1mm, CARD EDGE CONNECTOR

AMP INCORPORATED
 Harrisburg, PA 17105-3608

DATE: 02/98
 SIZE: A1
 PART NO: 145376

CUSTOMER DRAWING